

# ADC0801S040

Single 8 bits ADC, up to 40 MHz

Rev. 02 — 18 August 2008

Product data sheet

## 1. General description

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The ADC0801S040 is an 8-bit universal analog-to-digital converter (ADC) for video and general purpose applications. It converts the analog input signal from 2.7 V to 5.5 V into 8-bit binary-coded digital words at a maximum sampling rate of 40 MHz. All digital inputs and outputs are CMOS/Transistor-Transistor Logic (TTL) compatible. A sleep mode allows reduction of the device power consumption to 4 mW.

## 2. Features

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- 8-bit resolution
- Operation between 2.7 V and 5.5 V
- Sampling rate up to 40 MHz
- DC sampling allowed
- High signal-to-noise ratio over a large analog input frequency range (7.3 effective bits at 4.43 MHz full-scale input at  $f_{\text{clk}} = 40$  MHz)
- CMOS/TTL compatible digital inputs and outputs
- External reference voltage regulator
- Power dissipation only 30 mW (typical value)
- Low analog input capacitance, no buffer amplifier required
- Sleep mode (4 mW)
- No sample-and-hold circuit required

## 3. Applications

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- Video data digitizing
- Camera
- Camcorder
- Radio communication
- Car alarm system

## 4. Quick reference data

**Table 1. Quick reference data**

$V_{DDA} = V5$  to  $V6 = 3.3$  V;  $V_{DDD} = V3$  to  $V4 = 3.3$  V;  $V_{DDO} = V20$  to  $V11 = 3.3$  V;  $V_{SSA}$ ,  $V_{SSD}$  and  $V_{SSO}$  shorted together;  $V_{i(a)(p-p)} = 1.84$  V;  $C_L = 20$  pF;  $T_{amb} = 0$  °C to  $70$  °C; typical values measured at  $T_{amb} = 25$  °C unless otherwise specified.

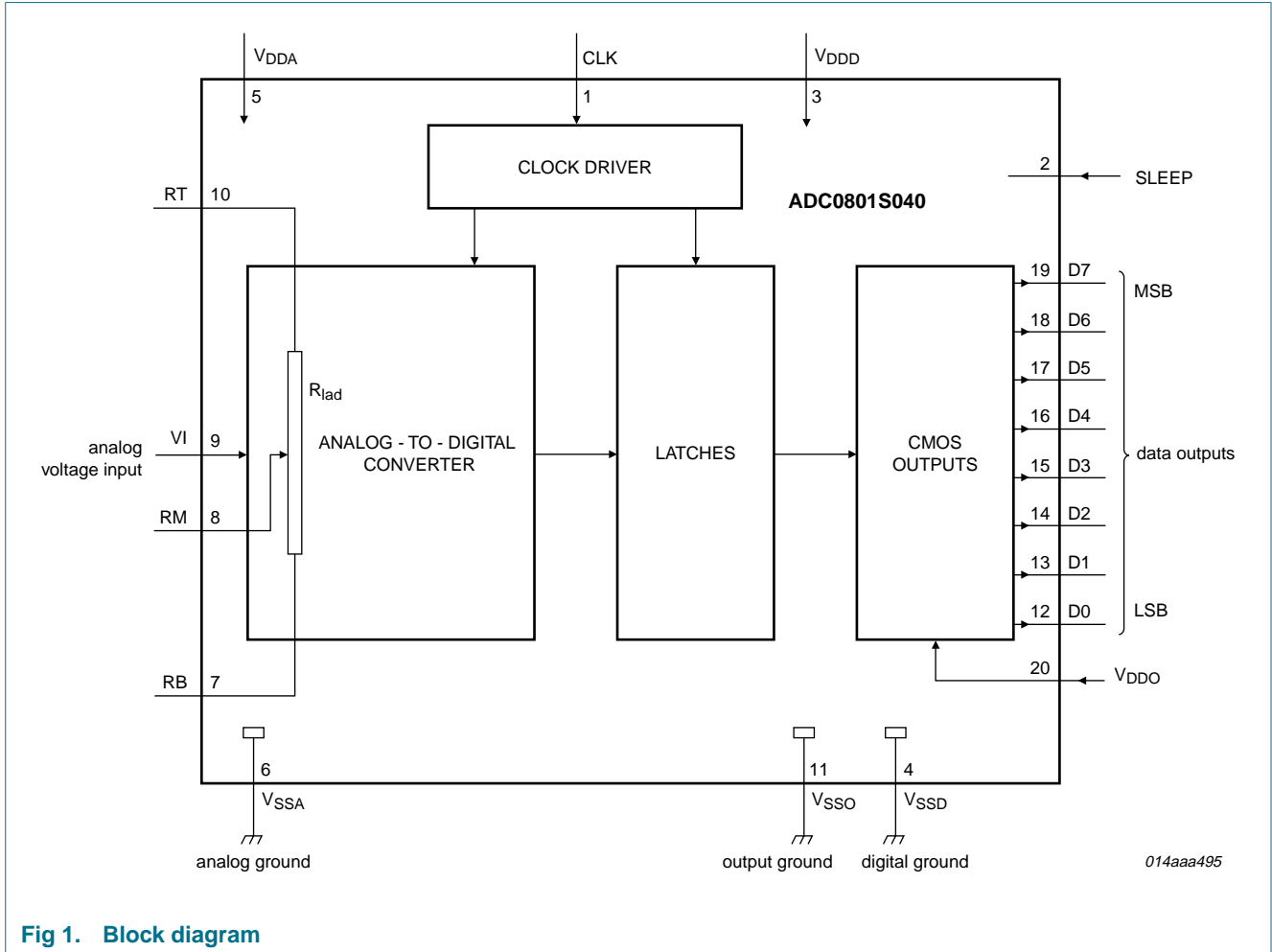
| Symbol          | Parameter                  | Conditions                                    | Min  | Typ        | Max        | Unit |
|-----------------|----------------------------|---|------|------------|------------|------|
| $V_{DDA}$       | analog supply voltage      |   | 2.7  | 3.3        | 5.5        | V    |
| $V_{DDD}$       | digital supply voltage     |   | 2.7  | 3.3        | 5.5        | V    |
| $V_{DDO}$       | output supply voltage      |   | 2.5  | 3.3        | 5.5        | V    |
| $\Delta V_{DD}$ | supply voltage difference  | $V_{DDA} - V_{DDD}$                           | -0.2 | -          | +0.2       | V    |
|                 |                            | $V_{DDD} - V_{DDO}$                           | -0.2 | -          | +2.25      | V    |
| $I_{DDA}$       | analog supply current      |   | -    | 4          | 6          | mA   |
| $I_{DDD}$       | digital supply current     |   | -    | 5          | 8          | mA   |
| $I_{DDO}$       | output supply current      | $f_{clk} = 40$ MHz; ramp input; $C_L = 20$ pF | -    | 1          | 2          | mA   |
| INL             | integral non-linearity     | ramp input; see <a href="#">Figure 6</a>      | -    | $\pm 0.5$  | $\pm 0.75$ | LSB  |
| DNL             | differential non-linearity | ramp input; see <a href="#">Figure 7</a>      | -    | $\pm 0.25$ | $\pm 0.5$  | LSB  |
| $f_{clk(max)}$  | maximum clock frequency    |   | 40   | -          | -          | MHz  |
| $P_{tot}$       | total power dissipation    | $V_{DDA} = V_{DDD} = V_{DDO} = 3.3$ V         | -    | 30         | 53         | mW   |

## 5. Ordering information

**Table 2. Ordering information**

| Type number   | Package |   | Version  |
|---------------|---------|---|----------|
|               | Name    | Description   |          |
| ADC0801S040TS | SSOP20  | plastic shrink small outline package; 20 leads; body width 4.4 mm | SOT266-1 |

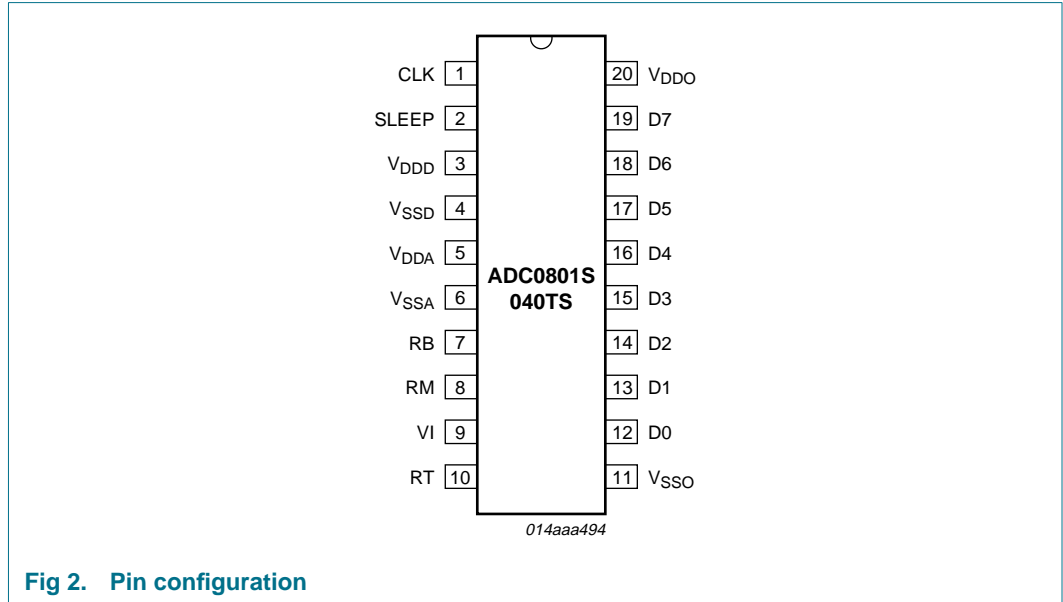
**6. Block diagram**



**Fig 1. Block diagram**

**7. Pinning information**

**7.1 Pinning**



**Fig 2. Pin configuration**

**7.2 Pin description**

**Table 3. Pin description**

| Symbol           | Pin | Description                                      |
|------------------|-----|--|
| CLK              | 1   | clock input                                      |
| SLEEP            | 2   | sleep mode input                                 |
| V <sub>DD</sub>  | 3   | digital supply voltage (2.7 V to 5.5 V)          |
| V <sub>SS</sub>  | 4   | digital ground                                   |
| V <sub>DDA</sub> | 5   | analog supply voltage (2.7 V to 5.5 V)           |
| V <sub>SSA</sub> | 6   | analog ground                                    |
| RB               | 7   | reference voltage BOTTOM input                   |
| RM               | 8   | reference voltage MIDDLE                         |
| VI               | 9   | analog input voltage                             |
| RT               | 10  | reference voltage TOP input                      |
| V <sub>SSO</sub> | 11  | output stage ground                              |
| D0               | 12  | data output; bit 0 (Least Significant Bit (LSB)) |
| D1               | 13  | data output; bit 1                               |
| D2               | 14  | data output; bit 2                               |
| D3               | 15  | data output; bit 3                               |
| D4               | 16  | data output; bit 4                               |
| D5               | 17  | data output; bit 5                               |

**Table 3. Pin description ...continued**

| Symbol           | Pin | Description   |
|------------------|-----|---|
| D6               | 18  | data output; bit 6  |
| D7               | 19  | data output; bit 7 (Most Significant Bit (MSB))           |
| V <sub>DDO</sub> | 20  | positive supply voltage for output stage (2.7 V to 5.5 V) |

## 8. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol                   | Parameter                        | Conditions  | Min      | Max              | Unit |
|--------------------------|----------------------------------|---|----------|------------------|------|
| V <sub>DDA</sub>         | analog supply voltage            |   | [1] -0.3 | +7.0             | V    |
| V <sub>DDD</sub>         | digital supply voltage           |   | [1] -0.3 | +7.0             | V    |
| V <sub>DDO</sub>         | output supply voltage            |   | [1] -0.3 | +7.0             | V    |
| ΔV <sub>DD</sub>         | supply voltage difference        | V <sub>DDA</sub> - V <sub>DDD</sub> ;<br>V <sub>DDD</sub> - V <sub>DDO</sub> ;<br>V <sub>DDA</sub> - V <sub>DDO</sub> | -0.1     | +4.0             | V    |
| V <sub>I</sub>           | input voltage                    | referenced to V <sub>SSA</sub>  | -0.3     | +7.0             | V    |
| V <sub>i(clk)(p-p)</sub> | peak-to-peak clock input voltage | referenced to V <sub>SSD</sub>  | -        | V <sub>DDD</sub> | V    |
| I <sub>O</sub>           | output current                   |   | -        | 10               | mA   |
| T <sub>stg</sub>         | storage temperature              |   | -55      | +150             | °C   |
| T <sub>amb</sub>         | ambient temperature              |   | -20      | +75              | °C   |
| T <sub>j</sub>           | junction temperature             |   | -        | 150              | °C   |

[1] The supply voltages V<sub>DDA</sub>, V<sub>DDD</sub> and V<sub>DDO</sub> may have any value between -0.3 V and +7.0 V provided that the supply voltage ΔV<sub>DD</sub> remains as indicated.

## 9. Thermal characteristics

**Table 5. Thermal characteristics**

| Symbol               | Parameter                                   | Condition   | Value | Unit |
|----------------------|---|-------------|-------|------|
| R <sub>th(j-a)</sub> | thermal resistance from junction to ambient | in free air | 120   | K/W  |

## 10. Characteristics

**Table 6. Characteristics**

V<sub>DDA</sub> = V5 to V6 = 3.3 V; V<sub>DDD</sub> = V3 to V4 = 3.3 V; V<sub>DDO</sub> = V20 to V11 = 3.3 V; V<sub>SSA</sub>, V<sub>SSD</sub> and V<sub>SSO</sub> shorted together; V<sub>i(a)(p-p)</sub> = 1.84 V; C<sub>L</sub> = 20 pF; T<sub>amb</sub> = 0 °C to 70 °C; typical values measured at T<sub>amb</sub> = 25 °C unless otherwise specified.

| Symbol           | Parameter              | Conditions | Min | Typ | Max | Unit |
|------------------|------------------------|------------|-----|-----|-----|------|
| <b>Supplies</b>  |                        |            |     |     |     |      |
| V <sub>DDA</sub> | analog supply voltage  |            | 2.7 | 3.3 | 5.5 | V    |
| V <sub>DDD</sub> | digital supply voltage |            | 2.7 | 3.3 | 5.5 | V    |
| V <sub>DDO</sub> | output supply voltage  |            | 2.5 | 3.3 | 5.5 | V    |

**Table 6. Characteristics ...continued**

$V_{DDA} = V5$  to  $V6 = 3.3$  V;  $V_{DDD} = V3$  to  $V4 = 3.3$  V;  $V_{DDO} = V20$  to  $V11 = 3.3$  V;  $V_{SSA}$ ,  $V_{SSD}$  and  $V_{SSO}$  shorted together;  $V_{i(a)(p-p)} = 1.84$  V;  $C_L = 20$  pF;  $T_{amb} = 0$  °C to  $70$  °C; typical values measured at  $T_{amb} = 25$  °C unless otherwise specified.

| Symbol          | Parameter                 | Conditions                                       | Min  | Typ | Max   | Unit |
|-----------------|---------------------------|--|------|-----|-------|------|
| $\Delta V_{DD}$ | supply voltage difference | $V_{DDA} - V_{DDD}$                              | -0.2 | -   | +0.2  | V    |
|                 |                           | $V_{DDD} - V_{DDO}$                              | -0.2 | -   | +2.25 | V    |
| $I_{DDA}$       | analog supply current     |  | -    | 4   | 6     | mA   |
| $I_{DDD}$       | digital supply current    |  | -    | 5   | 8     | mA   |
| $I_{DDO}$       | output supply current     | $f_{clk} = 40$ MHz; ramp input;<br>$C_L = 20$ pF | -    | 1   | 2     | mA   |
| $P_{tot}$       | total power dissipation   | $V_{DDA} = V_{DDD} = V_{DDO} = 3.3$ V            | -    | 30  | 53    | mW   |

**Inputs**

**Clock input CLK (Referenced to  $V_{SSD}$ )<sup>[1]</sup>**

|          |                          |                         |               |   |               |            |
|----------|--------------------------|-------------------------|---------------|---|---------------|------------|
| $V_{IL}$ | LOW-level input voltage  |                         | 0             | - | $0.3 V_{DDD}$ | V          |
| $V_{IH}$ | HIGH-level input voltage | $V_{DDD} \leq 3.6$ V    | $0.6 V_{DDD}$ | - | $V_{DDD}$     | V          |
|          |                          | $V_{DDD} > 3.6$ V       | $0.7 V_{DDD}$ | - | $V_{DDD}$     | V          |
| $I_{IL}$ | LOW-level input current  | $V_{clk} = 0.3 V_{DDD}$ | -1            | 0 | +1            | $\mu$ A    |
| $I_{IH}$ | HIGH-level input current | $V_{clk} = 0.7 V_{DDD}$ | -             | - | 5             | $\mu$ A    |
| $Z_i$    | input impedance          | $f_{clk} = 40$ MHz      | -             | 4 | -             | k $\Omega$ |
| $C_i$    | input capacitance        | $f_{clk} = 40$ MHz      | -             | 3 | -             | pF         |

**Input SLEEP (Referenced to  $V_{SSD}$ ); see Table 8**

|          |                          |                        |               |   |               |         |
|----------|--------------------------|------------------------|---------------|---|---------------|---------|
| $V_{IL}$ | LOW-level input voltage  |                        | 0             | - | $0.3 V_{DDD}$ | V       |
| $V_{IH}$ | HIGH-level input voltage | $V_{DDD} \leq 3.6$ V   | $0.6 V_{DDD}$ | - | $V_{DDD}$     | V       |
|          |                          | $V_{DDD} > 3.6$ V      | $0.7 V_{DDD}$ | - | $V_{DDD}$     | V       |
| $I_{IL}$ | LOW-level input current  | $V_{IL} = 0.3 V_{DDD}$ | -1            | - | -             | $\mu$ A |
| $I_{IH}$ | HIGH-level input current | $V_{IH} = 0.7 V_{DDD}$ | -             | - | +1            | $\mu$ A |

**Analog input VI (Referenced to  $V_{SSA}$ )**

|          |                          |                |   |    |   |            |
|----------|--------------------------|----------------|---|----|---|------------|
| $I_{IL}$ | LOW-level input current  | $V_I = V_{RB}$ | - | 0  | - | $\mu$ A    |
| $I_{IH}$ | HIGH-level input current | $V_I = V_{RT}$ | - | 9  | - | $\mu$ A    |
| $Z_i$    | input impedance          | $f_i = 1$ MHz  | - | 20 | - | k $\Omega$ |
| $C_i$    | input capacitance        | $f_i = 1$ MHz  | - | 2  | - | pF         |

**Reference voltages for the resistor ladder; see Table 7**

|                 |   |                       |                    |      |           |               |
|-----------------|---|-----------------------|--------------------|------|-----------|---------------|
| $V_{RB}$        | voltage on pin RB                       |                       | 1.1                | 1.2  | -         | V             |
| $V_{RT}$        | voltage on pin RT                       | $V_{RT} \leq V_{DDA}$ | 2.7                | 3.3  | $V_{DDA}$ | V             |
| $V_{ref(dif)}$  | differential reference voltage          | $V_{RT} - V_{RB}$     | 1.5                | 2.1  | 2.7       | V             |
| $I_{ref}$       | reference current                       |                       | -                  | 0.95 | -         | mA            |
| $R_{lad}$       | ladder resistance                       |                       | -                  | 2.2  | -         | k $\Omega$    |
| $TC_{Rlad}$     | ladder resistor temperature coefficient |                       | -                  | 4092 | -         | m $\Omega$ /K |
| $V_{offset}$    | offset voltage                          | BOTTOM                | <sup>[2]</sup> -   | 170  | -         | mV            |
|                 |   | TOP                   | <sup>[2]</sup> -   | 170  | -         | mV            |
| $V_{i(a)(p-p)}$ | peak-to-peak analog input voltage       |                       | <sup>[3]</sup> 1.4 | 1.76 | 2.4       | V             |

**Table 6. Characteristics ...continued**

$V_{DDA} = V5$  to  $V6 = 3.3$  V;  $V_{DDD} = V3$  to  $V4 = 3.3$  V;  $V_{DDO} = V20$  to  $V11 = 3.3$  V;  $V_{SSA}$ ,  $V_{SSD}$  and  $V_{SSO}$  shorted together;  $V_{i(a)(p-p)} = 1.84$  V;  $C_L = 20$  pF;  $T_{amb} = 0^\circ\text{C}$  to  $70^\circ\text{C}$ ; typical values measured at  $T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

| Symbol  | Parameter                  | Conditions  | Min             | Typ        | Max        | Unit          |
|---|----------------------------|---|-----------------|------------|------------|---------------|
| <b>Digital outputs D7 to D0 and IR (Referenced to <math>V_{SSD}</math>)</b> |                            |   |                 |            |            |               |
| $V_{OL}$  | LOW-level output voltage   | $I_O = 1$ mA  | 0               | -          | 0.5        | V             |
| $V_{OH}$  | HIGH-level output voltage  | $I_O = -1$ mA   | $V_{DDO} - 0.5$ | -          | $V_{DDO}$  | V             |
| $I_{OZ}$  | OFF-state output current   | $0.4$ V < $V_O$ < $V_{DDO}$                               | -20             | -          | +20        | $\mu\text{A}$ |
| <b>Clock input CLK; see Figure 4[1]</b>                                     |                            |   |                 |            |            |               |
| $f_{clk(max)}$  | maximum clock frequency    |   | 40              | -          | -          | MHz           |
| $t_{w(clk)H}$   | HIGH clock pulse width     |   | 9               | -          | -          | ns            |
| $t_{w(clk)L}$   | LOW clock pulse width      |   | 9               | -          | -          | ns            |
| <b>Analog signal processing (<math>f_{clk} = 40</math> MHz)</b>             |                            |   |                 |            |            |               |
| <b>Linearity</b>  |                            |   |                 |            |            |               |
| INL   | integral non-linearity     | ramp input; see Figure 6                                  | -               | $\pm 0.5$  | $\pm 0.75$ | LSB           |
| DNL   | differential non-linearity | ramp input; see Figure 7                                  | -               | $\pm 0.25$ | $\pm 0.5$  | LSB           |
| <b>Bandwidth</b>  |                            |   |                 |            |            |               |
| B   | bandwidth                  | full-scale sine wave [4]                                  | -               | 10         | -          | MHz           |
|   |                            | 75 % full-scale sine wave                                 | -               | 13         | -          | MHz           |
|   |                            | 50 % full-scale sine wave                                 | -               | 20         | -          | MHz           |
|   |                            | small signal at mid scale; $V_i = \pm 10$ LSB at code 128 | -               | 350        | -          | MHz           |
| <b>Input set response; see Figure 8[5]</b>                                  |                            |   |                 |            |            |               |
| $t_{s(LH)}$   | LOW to HIGH settling time  | full-scale square wave                                    | -               | 3          | 5          | ns            |
| $t_{s(HL)}$   | HIGH to LOW settling time  | full-scale square wave                                    | -               | 3          | 5          | ns            |
| <b>Harmonics; see Figure 9[6]</b>   |                            |   |                 |            |            |               |
| THD   | total harmonic distortion  | $f_i = 4.43$ MHz  | -               | -50        | -          | dB            |
| <b>Signal-to-Noise ratio; see Figure 9[6]</b>                               |                            |   |                 |            |            |               |
| S/N   | signal-to-noise ratio      | without harmonics; $f_i = 4.43$ MHz                       | -               | 47         | -          | dB            |
| <b>Effective bits; see Figure 9[6]</b>                                      |                            |   |                 |            |            |               |
| ENOB  | effective number of bits   | $f_i = 300$ MHz   | -               | 7.8        | -          | bits          |
|   |                            | $f_i = 4.43$ MHz  | -               | 7.3        | -          | bits          |
| <b>Differential gain[7]</b>   |                            |   |                 |            |            |               |
| $G_{dif}$   | differential gain          | PAL modulated ramp  | -               | 1.5        | -          | %             |

**Table 6. Characteristics ...continued**

$V_{DDA} = V5$  to  $V6 = 3.3$  V;  $V_{DDD} = V3$  to  $V4 = 3.3$  V;  $V_{DDO} = V20$  to  $V11 = 3.3$  V;  $V_{SSA}$ ,  $V_{SSD}$  and  $V_{SSO}$  shorted together;  $V_{i(a)(p-p)} = 1.84$  V;  $C_L = 20$  pF;  $T_{amb} = 0$  °C to  $70$  °C; typical values measured at  $T_{amb} = 25$  °C unless otherwise specified.

| Symbol  | Parameter                       | Conditions         | Min | Typ  | Max | Unit |
|---|---------------------------------|--------------------|-----|------|-----|------|
| <b>Differential phase<sup>[7]</sup></b>   |                                 |                    |     |      |     |      |
| $\phi_{dif}$  | differential phase              | PAL modulated ramp | -   | 0.25 | -   | deg  |
| <b>Timing (<math>f_{clk} = 40</math> MHz; <math>C_L = 20</math> pF); see <a href="#">Figure 4<sup>[8]</sup></a></b> |                                 |                    |     |      |     |      |
| $t_{d(s)}$  | sampling delay time             |                    | -   | -    | 5   | ns   |
| $t_{h(o)}$  | output hold time                |                    | 5   | -    | -   | ns   |
| $t_{d(o)}$  | output delay time               | $V_{DDO} = 4.75$ V | 8   | 12   | 15  | ns   |
|   |                                 | $V_{DDO} = 3.15$ V | 8   | 17   | 20  | ns   |
|   |                                 | $V_{DDO} = 2.7$ V  | 8   | 18   | 21  | ns   |
| <b>3-state output delay times; see <a href="#">Figure 5</a></b>   |                                 |                    |     |      |     |      |
| $t_{dHZ}$   | active HIGH to float delay time |                    | -   | 14   | 18  | ns   |
| $t_{dZL}$   | float to active LOW delay time  |                    | -   | 16   | 20  | ns   |
| $t_{dZH}$   | float to active HIGH delay time |                    | -   | 16   | 20  | ns   |
| $t_{dLZ}$   | active LOW to float delay time  |                    | -   | 14   | 18  | ns   |

- [1] In addition to a good layout of the digital and analog ground, it is recommended that the rise and fall times of the clock must not be less than 1 ns.
- [2] Analog input voltages producing code 0 up to and including code 255:
  - a)  $V_{offset\ BOTTOM}$  is the difference between the analog input which produces data equal to 00 and the reference voltage on pin RB ( $V_{RB}$ ) at  $T_{amb} = 25$  °C.
  - b)  $V_{offset\ TOP}$  is the difference between the reference voltage on pin RT ( $V_{RT}$ ) and the analog input which produces data outputs equal to code 255 at  $T_{amb} = 25$  °C.
- [3] To ensure the optimum linearity performance of such a converter architecture the lower and upper extremities of the converter reference resistor ladder are connected to pins RB and RT via offset resistors  $R_{OB}$  and  $R_{OT}$  as shown in [Figure 3](#).
  - a) The current flowing into the resistor ladder is  $I = \frac{V_{RT} - V_{RB}}{R_{OB} + R_L + R_{OT}}$  and the full-scale input range at the converter, to cover code 0 to 255 is  $V_I = R_L \times I_L = \frac{R_L}{R_{OB} + R_L + R_{OT}} \times (V_{RT} + V_{RB}) = 0.838 \times (V_{RT} - V_{RB})$
  - b) Since  $R_L$ ,  $R_{OB}$  and  $R_{OT}$  have similar behavior with respect to process and temperature variation, the ratio  $\frac{R_L}{R_{OB} + R_L + R_{OT}}$  will be kept reasonably constant from device to device. Consequently variation of the output codes at a given input voltage depends mainly on the difference  $V_{RT} - V_{RB}$  and its variation with temperature and supply voltage. When several ADCs are connected in parallel and fed with the same reference source, the matching between each of them is optimized.
- [4] The analog bandwidth is defined as the maximum input sine wave frequency which can be applied to the device. No glitches greater than 2 LSB, nor any significant attenuation is observed in the reconstructed signal.
- [5] The analog input settling time is the minimum time required for the input signal to be stabilized after a sharp full-scale input (square wave signal) in order to sample the signal and obtain correct output data.
- [6] Effective bits are obtained via a Fast Fourier Transform (FFT) treatment taking 8000 acquisition points per equivalent fundamental period. The calculation takes into account all harmonics and noise up to half of the clock frequency (Nyquist frequency). Conversion to signal-to-noise ratio:  $S/N = ENOB \times 6.02 + 1.76$  dB.
- [7] Measurement carried out using video analyzer VM700A, where video analog signal is reconstructed through a DAC.
- [8] Output data acquisition: the output data is available after the maximum delay time of  $t_{d(o)}$ .



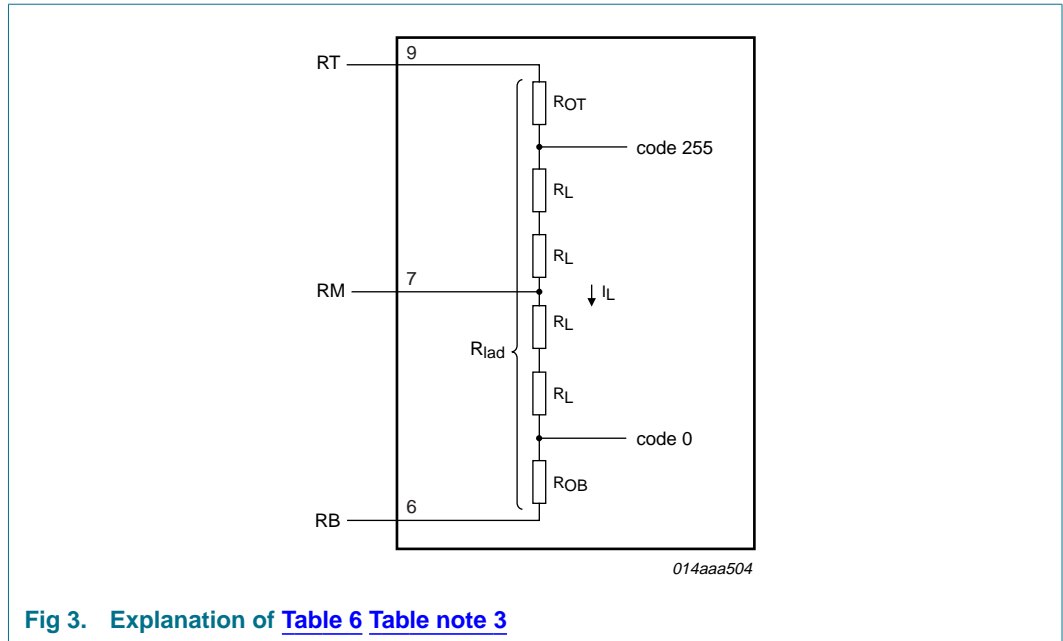


Fig 3. Explanation of [Table 6 Table note 3](#)

## 11. Additional information relating to [Table 6](#)

**Table 7. Output coding and input voltage (typical values; referenced to V<sub>SSA</sub>)**

| Code      | V <sub>i(a)(p-p)</sub> (V) | Binary outputs D7 to D0 |
|-----------|----------------------------|-------------------------|
| Underflow | < 1.37                     | 00 0000 00              |
| 0         | 1.37                       | 00 0000 00              |
| 1         | -                          | 00 0000 01              |
| ↓         | -                          | ↓                       |
| 254       | -                          | 11 11 11 10             |
| 255       | 3.13                       | 11 11 11 11             |
| Overflow  | > 3.13                     | 11 11 11 11             |

**Table 8. Mode selection**

| SLEEP | D7 to D0       | I <sub>DDA</sub> + I <sub>DDD</sub> (typ) |
|-------|----------------|---|
| 1     | high impedance | 1.2 mA                                    |
| 0     | active         | 9 mA                                      |

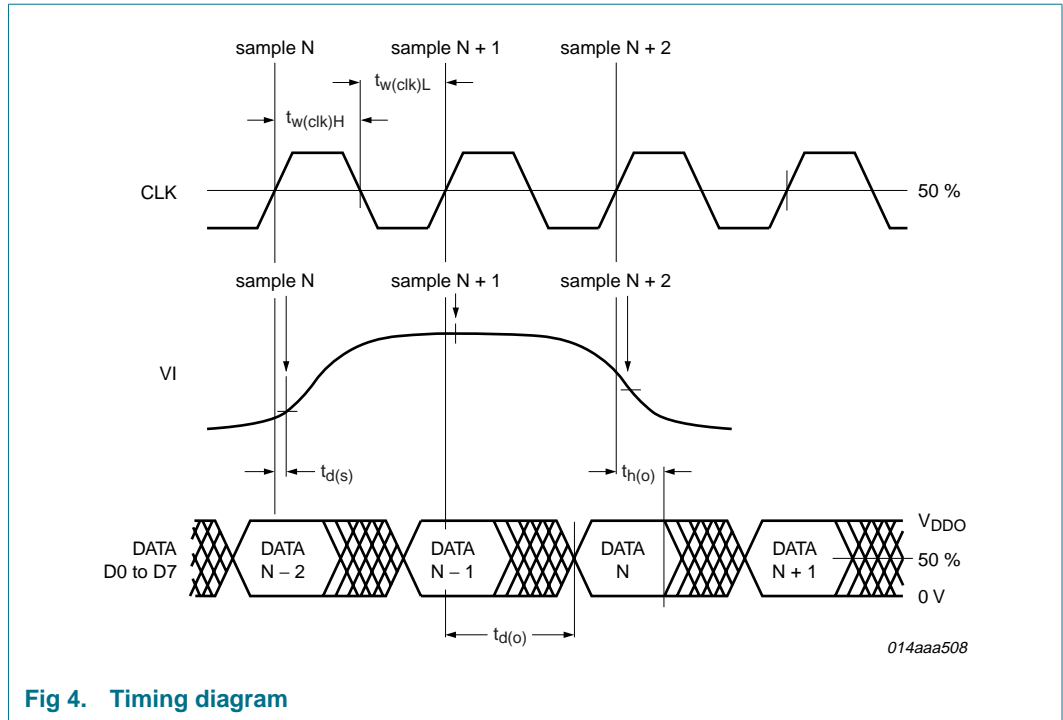
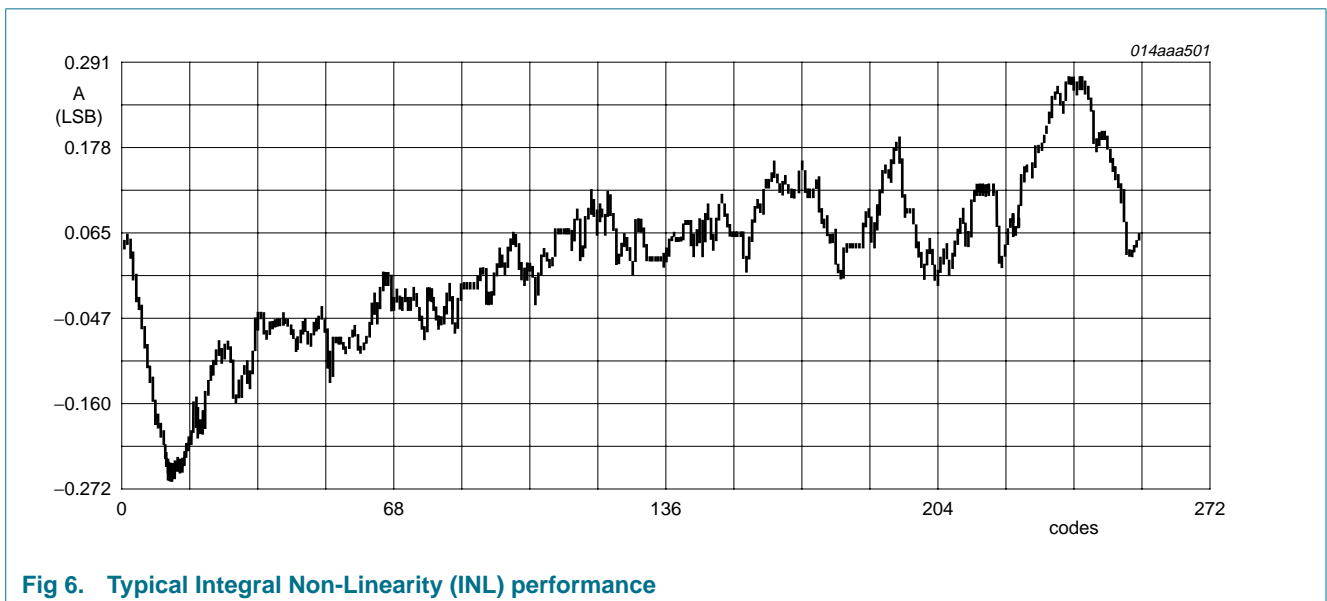
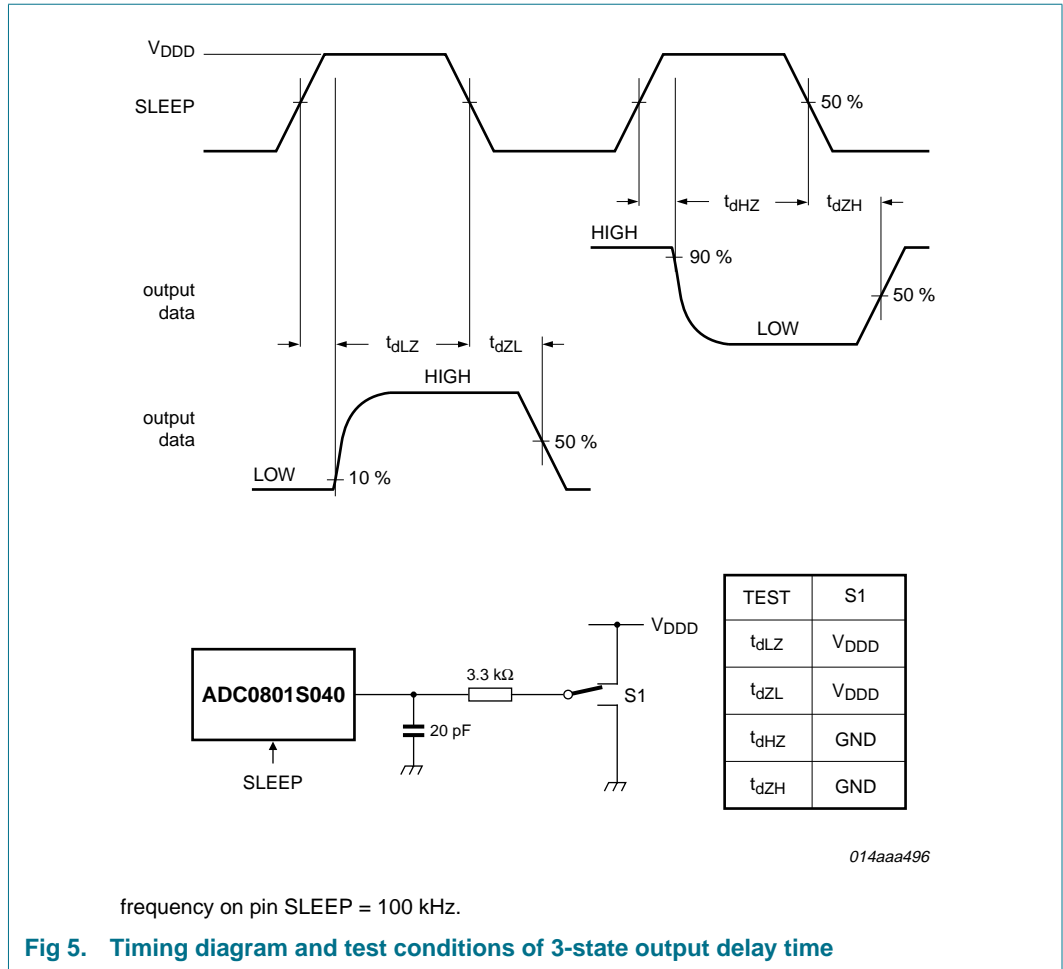


Fig 4. Timing diagram



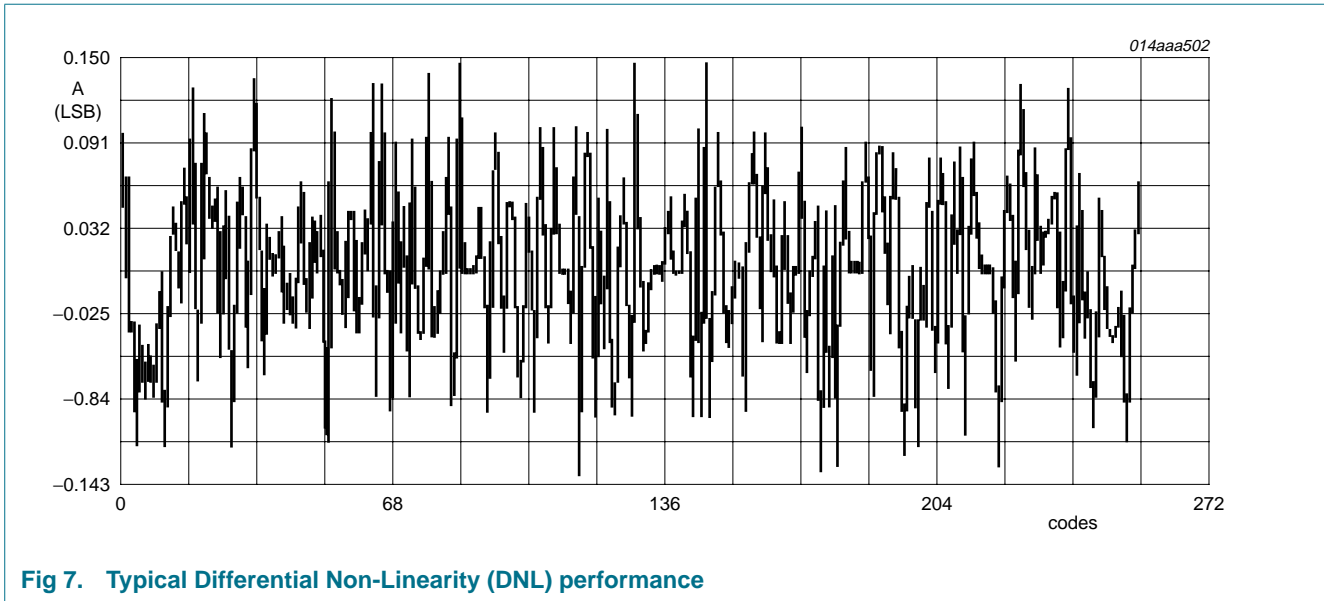


Fig 7. Typical Differential Non-Linearity (DNL) performance

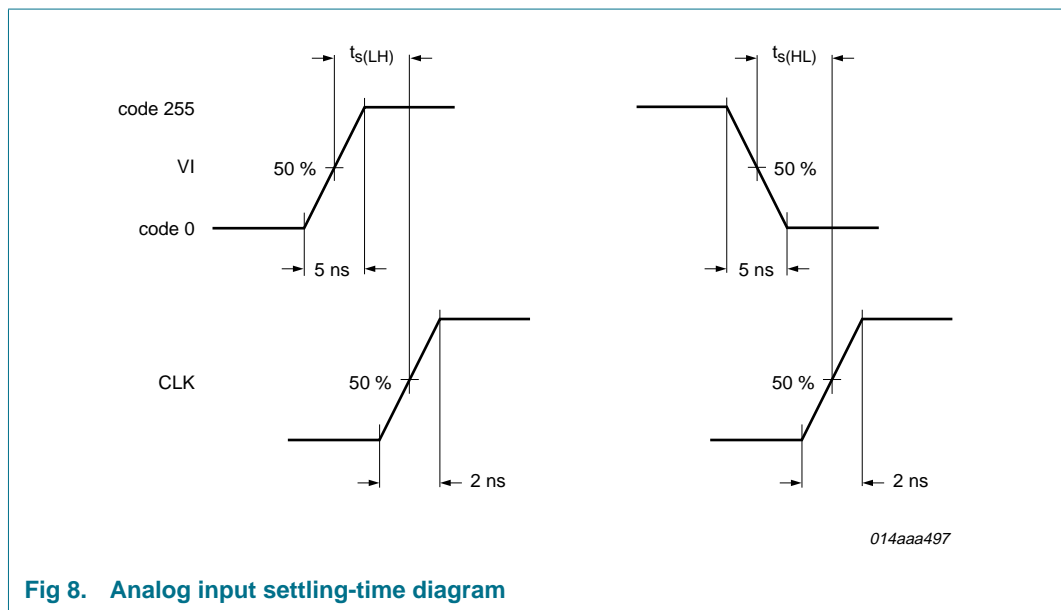
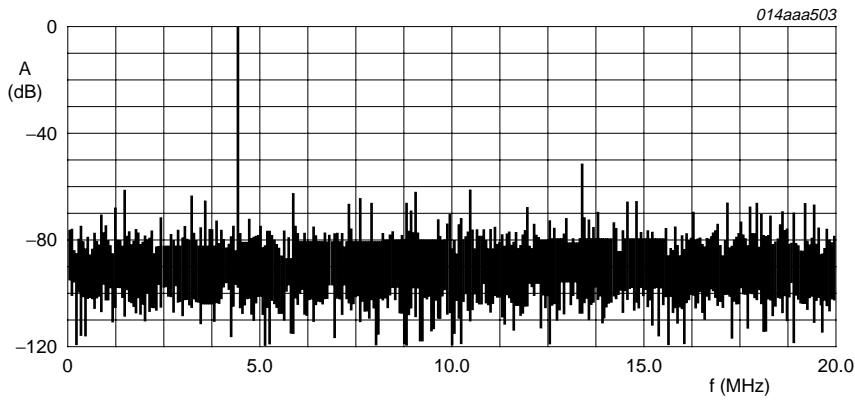


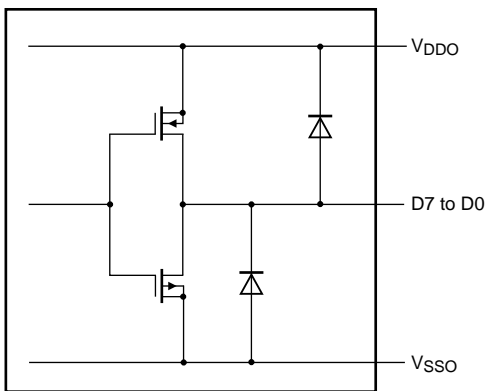
Fig 8. Analog input settling-time diagram



Effective bits: 7.32; THD = -51.08 dB.

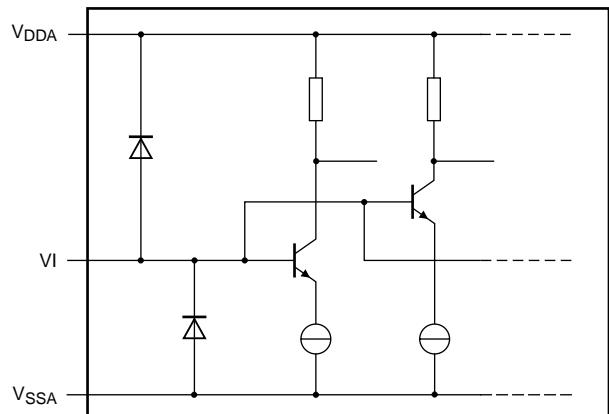
Harmonic levels (dB): 2nd = -68.99; 3rd = -51.62; 4th = -66.05; 5th = -63.23; 6th = -72.79.

Fig 9. Typical fast Fourier transform ( $f_{clk} = 40 \text{ MHz}$ ;  $f_i = 4.43 \text{ MHz}$ )



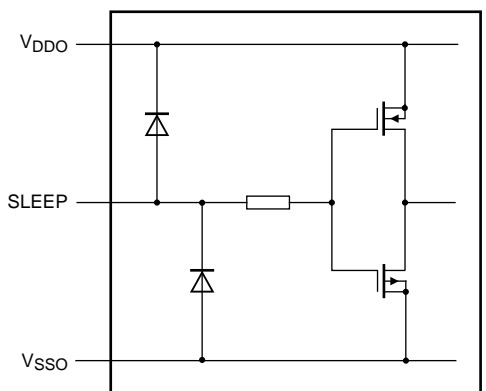
014aaa498

Fig 10. CMOS data outputs



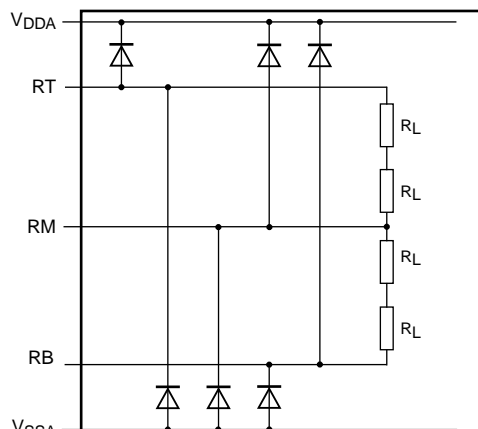
014aaa505

Fig 11. VI analog input



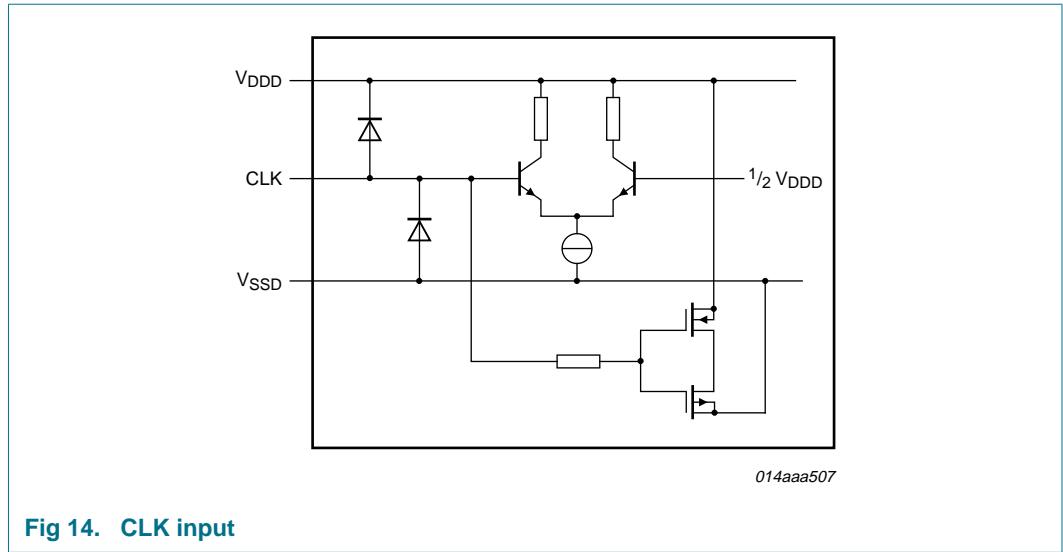
014aaa499

Fig 12. SLEEP 3-state input



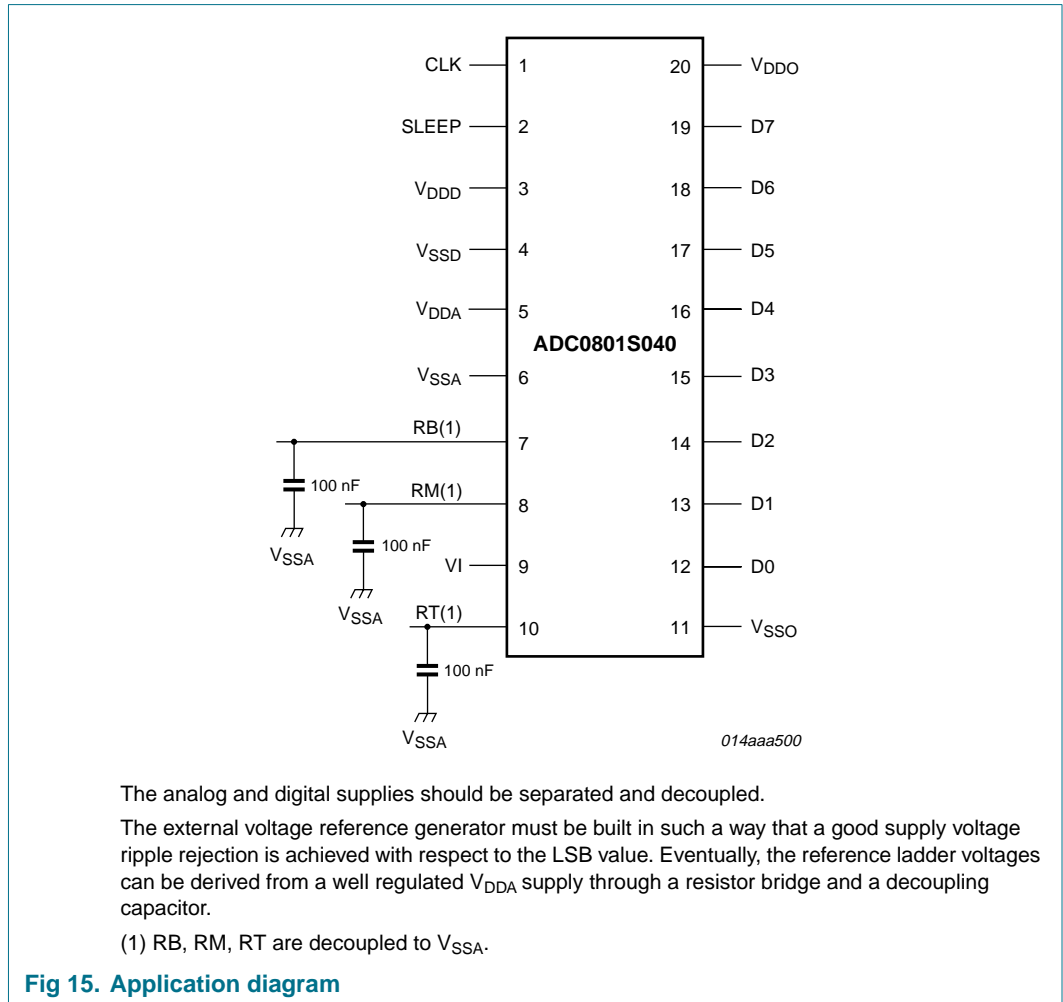
014aaa506

Fig 13. RB, RM and RT inputs



**12. Application information**

**12.1 Application diagrams**



**Fig 15. Application diagram**

13. Package outline

SSOP20: plastic shrink small outline package; 20 leads; body width 4.4 mm

SOT266-1

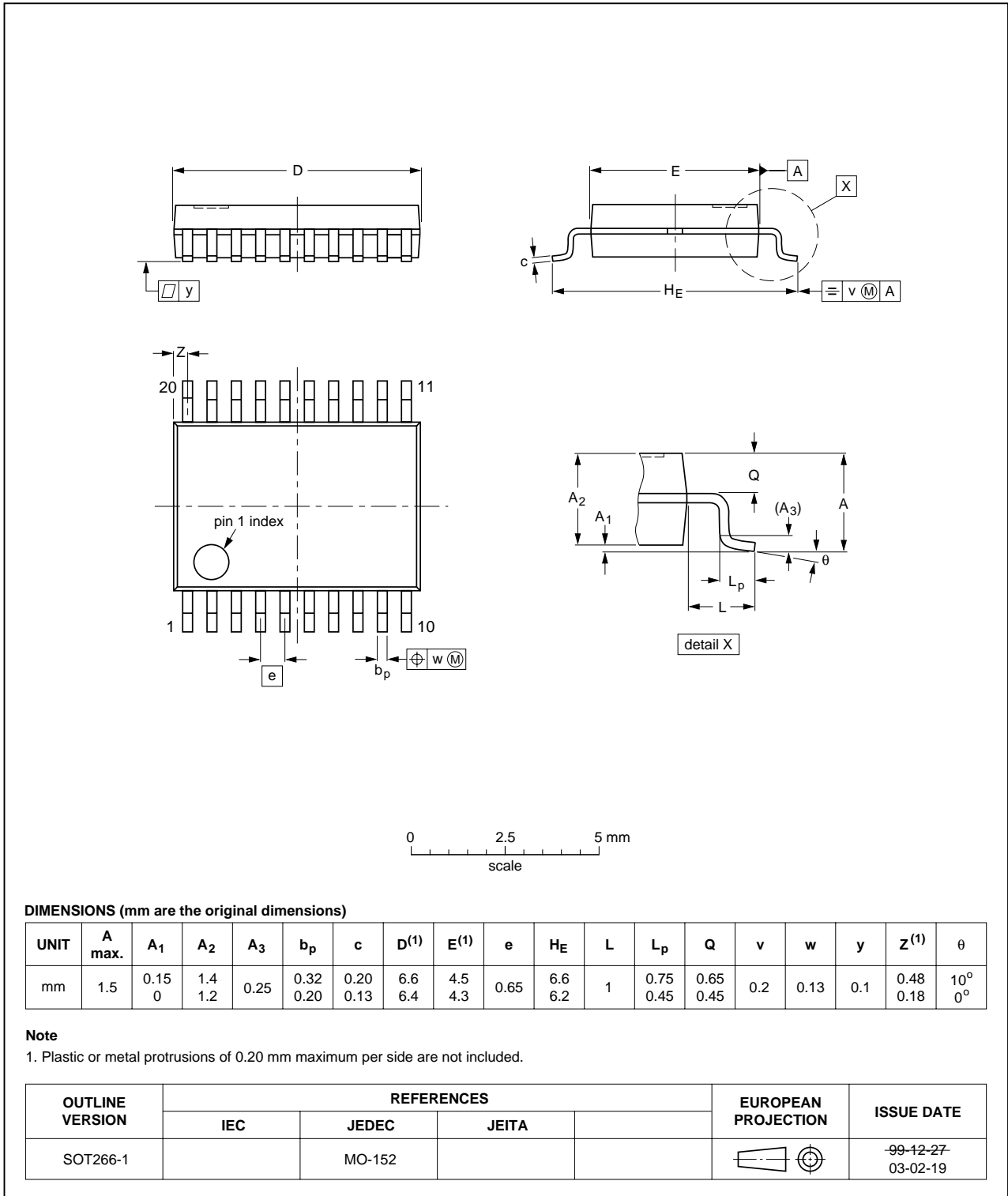


Fig 16. Package outline SOT266-1 (SSOP20)



## 14. Revision history

**Table 9. Revision history**

| Document ID    | Release date | Data sheet status   | Change notice | Supersedes    |
|----------------|--------------|---|---------------|---------------|
| ADC0801S040_2  | 20080818     | Product data sheet  | -             | ADC0801S040_1 |
| Modifications: |              | <ul style="list-style-type: none"><li>• Corrections made to table notes in <a href="#">Figure 1</a>.</li><li>• Corrections made to <a href="#">Table 3</a>.</li><li>• Corrections made to symbol in <a href="#">Table 4</a>.</li><li>• Corrections made to <a href="#">Table 6</a>.</li><li>• Corrections made to <a href="#">Figure 13</a></li></ul> |               |               |
| ADC0801S040_1  | 20080612     | Product data sheet  | -             | -             |

## 15. Legal information

### 15.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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